

Specification for TFT

AFL240135A0-1.14INTM-ANO



Revision V0

А	Orient Display
FL	ТFТ Туре
240135	Resolution 240 x 135
A0	Serial A0
1.14	1.14", Module Dimension 33.0 x 28.0 x 5.0mm
1	IPS Display
Ν	Top: -20~+70°C; Tstr: -30~+80°C
Т	Transmissive
Μ	Normal Brightness, 300cd/m2
1	Controller <u>ST7789V</u>
ANO	SPI Interface + compatible Arduino













DOCUMENT REVISION HISTORY:

DATE	PAGE	DESCRIPTION
2020.10.3	-	First release

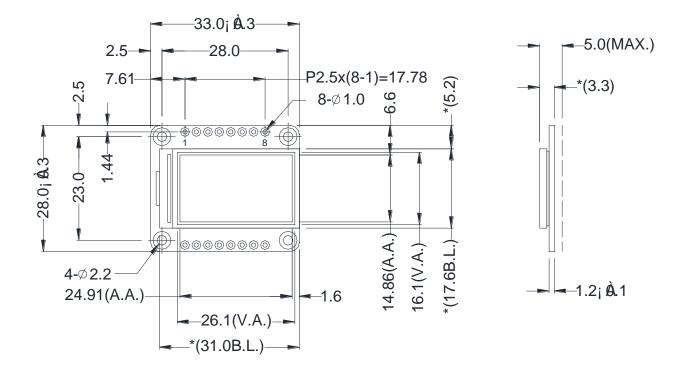
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1. General Specification

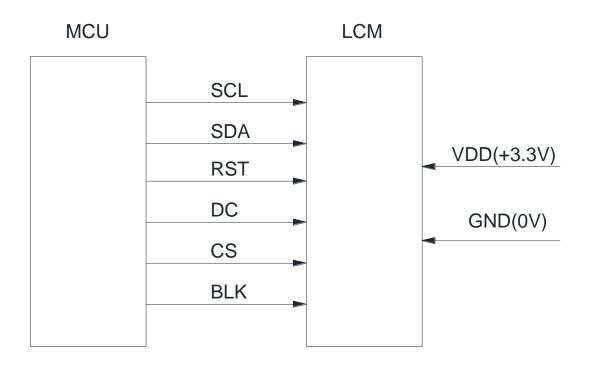
Item	Dimension	Unit
Module dimension	33.0 x 28.0 x 5.0(MAX)	mm
View area	26.1 x 16.1	mm
Active area	24.91 x 14.86	mm
Dot pitch	0.103 x 0.110	mm
Number of Dots	240 x 135(RGB)	dots
LCD TYPE	TFT, Transmissive	
Top Polarizer Type	Glare	
View direction	All View	
Drive IC	ST7789V	
Interface Type	SPI 4-wires	
Backlight Type	1 White LED	
Touch Panel	Not Available	

2. Mechanical Drawing



- *ST7789V or equivalent
- *()dimension for reference only

3. Block Diagram



4. Interface Pin Function

Pin No.	Symbol	Level	Description
1	GND	0V	Ground
2	V _{DD}	3.3V	Supply Voltage for logic
3	SCL	H/L	Serial Clock
4	SDA	H/L	Serial Data
5	RST	H/L	Reset, signal is active low
6	DC	H/L	H:Display data or Parameter, L:Command Data
7	CS	H/L	Chip Select, signal is active low
8	BLK	H/L	Backlight control, H:turn on ,L: turn off

5.Absolute Maximum Ratings

Item	Symbol	Min	Max	Unit
Supply Voltage	VDD	-0.3	4.6	V
Input Voltage(logic input)	V _{In}	-0.3	VDD+0.5	V
Operating Temperature	Тор	-20	70	°C
Storage Temperature	Tstr	-30	80	°C

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any time. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

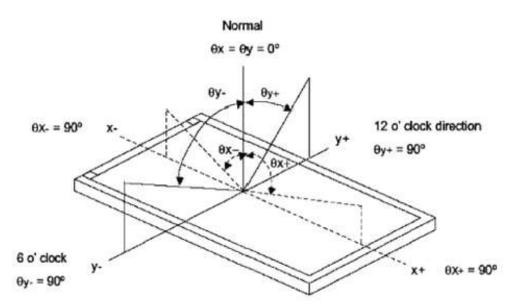
6. Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage	V _{DD}	_	2.7	3.3	3.6	V
Input Voltage for Logic	V _{io}	-	0	-	3.6	V
Input High Volt.	V _{IH}	—	$0.7 V_{DD}$		V _{DD}	V
Input Low Volt.	V _{IL}	_	V _{SS}		0.3 V _{DD}	V

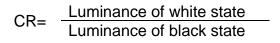
7. Optical Characteristics

Item		Symbol	Condition	Min	Тур	Max	Unit
Luminance		L	-	300			Cd/m ²
Contrast Ratio		CR	θ=0°		500:1		_
Daenonea Tima		T on	25℃		30	-	ma
Response Time		T off	23 C		50		ms
		Wx		0.255	-	0.330	
	White	W _Y		0.255	-	0.330	
	Ded	R _x					
Color Filter	Red	R _Y					
Chromacicity	Green	G _x					
		G _Y					
	Dhua	Bx					
	Blue	B _Y					
	1.1	Θ _{x-}	_		80		
X ⁷	Hor.	Θ _{x+}	00.40		80		
Viewing angle	Man	Θ _{y+}	CR>10		80		
	Ver.	Θ _{y-}			80		
Uniformity		Un	—	80	-		%

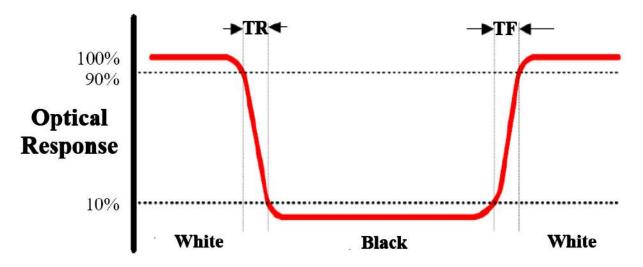
Note1:Definition of Viewing Angle θx and θy :



Note 2: Definition of contrast ratio CR:



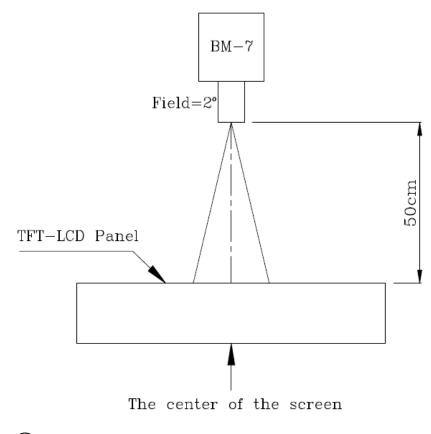
Note 3: Definition of Response Time(Tr,Tf):



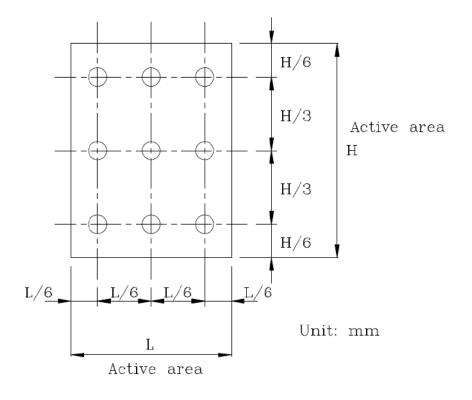
Note 4: Definition of Luminance:

1 The Brightness Test Equipment Setup

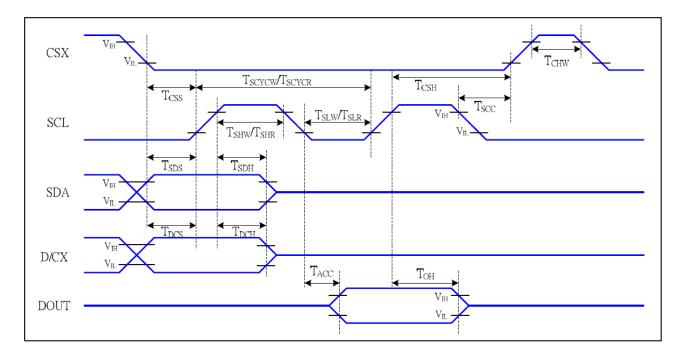
Field=2°(As measuring "black" image, field=2°is the best testing condition)



2 The Brightness Test Point Setup



8. Timing Characteristics



Signal	Symbol	Parameter	MIN	MAX	Unit	Description
	T _{CSS}	Chip select setup time (write)	15		ns	
	T _{CSH}	Chip select hold time (write)	15		ns	
CSX	T _{CSS}	Chip select setup time (read)	60		ns	
	T _{SCC}	Chip select hold time (read)	65		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
	T _{SCYCW}	Serial clock cycle (Write)	66		ns	-write command & data
	T _{SHW}	SCL "H" pulse width (Write)	15		ns	ram
SCL	T _{SLW}	SCL "L" pulse width (Write)	15		ns	lan
301	T _{SCYCR}	Serial clock cycle (Read)	150		ns	-read command & data
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	ram
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	Tam
D/CX	T _{DCS}	D/CX setup time	10		ns	
DICX	T _{DCH}	D/CX hold time	10		ns	
SDA		Data setup time	10		ns	
(DIN)	T_{SDH}	Data hold time	10		ns	
DOUT	T _{ACC}	Access time	10	50	ns	For maximum CL=30pF
0001	T _{OH}	Output disable time	15	50	ns	For minimum CL=8pF

9.Standard Specification for Reliability

9.1Standard Specification for Reliability of LCD Module

No	Test Item	Condition	Remarks
1	High Temperature	$Ts = +70^{\circ}C$, 96 hours	IEC60068-21:2007
	Operation		GB2423.2-2008
2	Low Temperature	$Ts = -20^{\circ}C$, 96 hours	IEC60068-2-1:2007
	Operation		GB/2423.1-2008
3	High Temperature	$Ta = +80^{\circ}C$, 96 hours	IEC60068-21:2007
	Storage		GB/2423.2-2008
4	Low Temperature	$Ta = -30^{\circ}C$, 96 hours	IEC60068-21:2007
	Storage		GB/2423.1-2008
5	Storage at High	$Ta = +60^{\circ}C$, 90% RH max,48 hours	IEC60068-2-78 :2001
	Temperature and		GB/T2423.3—2006
	Humidity		
6	Thermal	-20°C 30 min~+70°C 30 min,	Start with cold
	Shock	Change time:5min, 10 Cycle	temperature,
	(nonoperation)		End with high

			temperature, IEC60068-214:1984,
			GB/2423.22-2002
7	ESD	C=150pF,R=330 Ω,5point/panel	IEC61000-42:2001
		Air: \pm 8Kv,5times;	GB/T17626.2-2006
		Contact: \pm 4Kv,5times	
		(Environment:15°C~35°C,	
		30%~60%.86Kpa~106Kpa)	
8	Vibration Test	Frequency range:10~55Hz	IEC60068-2-6:1982
		Stroke:1.5mm	GB/T2423.101995
		Sweep:10Hz~55Hz~10Hz	
		2 hours for each direction of X.Y.Z	
		(6 hours for total)	
9	Mechanical	Half Sine Wave60G	IEC60068-2-27:1987
	Shock (Non	$6ms, \pm X, \pm Y, \pm Z$	GB/T2423.5—1995
	Op)	3times for each direction	
10	Package Drop	Height:80cm,	IEC60068-2-32:1990
	Test	1corner,3 edges,6 surfaces	GB/T2423.8—1995

Note1: Ts is the temperature of panel's surface.

Note2: Ta is the ambient temperature of sample.

9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in

Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria
1	Current	Refer To	The current consumption should conform to the
	Consumption	Specification	product specification.
2	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
3	Appearance	Visual inspection	Defect free.

9.3MTBF

deterioration within 50,000 hours under ordinary operating and storage
conditions room temperature $(25 \pm 5 \degree C)$, normal humidity $(50 \pm 10\% RH)$, and in area not exposed to direct sun light.

10.Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by ODNA.

10.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

Electrical-Optical Characteristics: According to the individual specification to test the product.

Appearance Characteristics: According to the individual specification to test the product.

Reliability Characteristics: According to the definition of reliability on the specification for testing products.

10.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

Test method: According to MIL-STD105E.General Inspection Level II take a

single Time. The defects classify of AQL as following: Major defect: AQL = 0.65Minor defect: AQL = 1.5Total defects: AQL = 1.5

10.3 Non-conforming Analysis & Deal With Manners

10.3.1 Non-conforming Analysis

Purchaser should provide the data detail of non-conforming sample and the non-conforming.

After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.

If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

10.3.2 Disposition of non-conforming

If any product defect be found during assembling, supplier must change the good for every defect after confirmation.

Both supplier and customer should analyze the reason and discuss the disposition of

non-conforming when the reason of nonconforming is not sure.

10.4 Agreement items

Both parties should negotiate together when the following problems happen. There is any problem of standard of quality assurance, and both sides should agree that it must be modified.

There is any argument item which does not record in the standard of quality assurance.

Any other special problem.

10.5 Standard of The Product Appearance Test

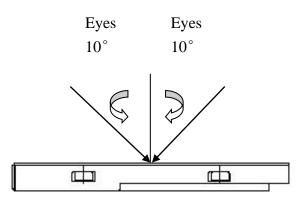
10.5.1Manner of appearance test

The test must be under $20W \times 2$ or 40W fluorescent light, and the distance of view must be at 30 ± 5 cm.

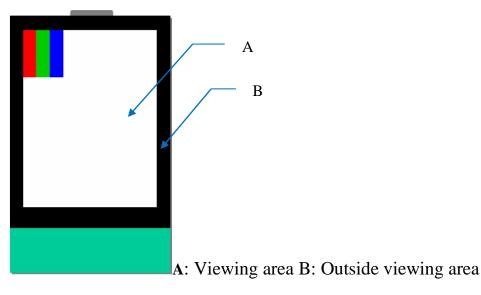
When test the model of transmissive product must add the reflective plate.

The test direction is base on around 10° of vertical line.

Temperature: 25±5℃ Humidity: 60±10%RH



Definition of area:



10.5.2 Basic principle

When the standard can not be described, AQL will be applied.

The sample of the lowest acceptable quality level must be negotiated by both

supplier and customer when any dispute happened.

New item must be added on time when it is necessary.

10.6 Inspection Specification

NO.	Item	Criterion			_		AQL
1	Electrical	1.1 Missing vertical, horizo	ontal segment, segment contrast defect.			0.65	
	Testing	1.2 Missing character, dot of	or icon.				
		1.3 Display malfunction.1.4 No function or no display.1.5 Convert converting and the set of the					
		1.5 Current consumption ex	-	luct spec	ificati	ons.	
	1.6 LCD viewing angle defect.						
		1.7 Mixed product types.					
2	D1 1	1.8 Flicker			- 0.		1.5
2	Black or	2.1 White and black or colo	or spots on	display	≥ 0.2	25mm, no	1.5
	White	more than					
	spots or Bright	Five spots.	4 4	,	• .1 •	2	
	spots or	2.2 Densely spaced: No mo	re than thre	ee spots	within	i 3mm.	
	Color spots						
	on LCD						
	(Display						
	only)						
3	LCD and 3.1 Round type: As following drawing					1.5	
	Touch	$\Phi = (X+Y) / 2$					
	Panel black		Size(mm)	Acc	eptable Q'ty	
	spots,	X	$\Phi \leq 0.10$)	Acc	ept no dense	
	white	→ _ ← ↓	0.10< Φ	≦0.20	2		
	spots, contaminati	• <u> </u>	0.20< Φ	≦0.25	2		
		T T	0.25< Φ	≦0.30	1		
	on (non – display)		0.30< Φ		0		
	uispiay)	* Densely spaced: No more			hin 3r	nm.	
		3.2 Line type: (As following drawing)				1.5	
			0 0,				
			Length(Width(mm)	Acceptable	
			mm)			Q'ty	
				$W \leq 0.0$	02	Accept no	
		∠¥ w				dense	
		\sim $+$ $-$	L≦3.0	0.02 <v< td=""><td>V≦</td><td>2</td><td></td></v<>	V≦	2	
		→ _L		0.05			
	$L \le 2.5 \begin{array}{c} 0.03 < W \le \\ 0.08 \end{array} 2 \\ \hline \end{array}$					2	
				0.08 <v< td=""><td>V</td><td>Rejection</td><td></td></v<>	V	Rejection	
		* D 1 1 1 1			• •		
		* Densely spaced: No more	e than two l	ines with	un 3n	ım.	

NO.	Item	Criterion			AQL
4	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in	Size $\Phi(mm)$	Acceptable Q'ty	1.5
			$\Phi \le 0.30$	Accept no dense	
		specify direction	$0.30 < \Phi \le 0.50$) 0	
			0.50< Φ ≦ 1.00) 0	
			1.00< Φ	0	
			Total Q' ty	0	
5	Scratches	Follow NO.3 -2 Line 7			
6	Chipped glass	k: Seal width t: Glass t L: Electrode pad lengt 6.1 General glass chip 6.1.1 Chip on panel su x z: Chip thickness $Z \le 1/2t$ $1/2t < z \le 2t$ \odot Unit: mm		ength a panels: x: Chip length $x \leq 2MM$ $x \leq 2MM$	

NO.	Item	Criterion		AQL
7	Glass crack	Symbols: x: Chip length y: Chip width z: Chi k: Seal width t: Glass thickness a: I L: Electrode pad length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:	1	1.5
		y: Chip widthx: Chip len $y \le 0.5 \text{mm}$ $x \le 2 \text{MM}$ 7.2.2Non-conductive portion:	ngthz: Chip thickness $0 < z \le t$	
		y z z	y z z	
		y: Chip widthx: Chip left $y \leq L$ $x \leq 2MM$ \odot If there chipped area touches the must remain and be inspected accord specifications. \odot If the product will be heat sealed mark must mot be damaged.7.2.3 Substrate protuberance and in y y y y y y y	$0 < z \le t$ e ITO terminal, over 2/3 of the ITOrding to electrode terminaled by the customer, the alignmenteternal crackidth x: length	

NO.	Item	Criterion	AQL		
8	Cracked glass	No crack is allowed.			
9	Backlight elements	9.1 Illumination source flickers when lit.9.2 Spots or scratches that appear when lit must be judged.Using LCD spot, lines and contamination standards.9.3 Backlight doesn't light or color is wrong.			
10	Bezel	No scratches with W>0.1 and Length>2.5mm.			
11	PCB、 COB	11.1 COB seal may not have pinholes larger than 0.2mm or contamination.	1.5		
		11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram.	1.5 1.5		
		11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places.	1.5		
		11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts.	0.65		
		11.6 The jumper on the PCB should conform to the product characteristic chart.	0.65		
12	FPC	FPC damage per IPC guidelines.(IPC-A-610) Nicks or damage along the edges of the flexible printed cir-cuitry and cutouts,providing the penetration does not exceed 50% of the distance from the edge to the nearest conductor to 2.5mm[0.1in], Whichever is less.	1.5		
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle.	1.5		
		13.2 No short circuits in components on PCB or FPC.	1.5		
		13.3 Soldering per IPC guidelines.(IPC-A-610)	0.65		

NO.	Item	Criterion			AQL			
14	Touch	Symbols: 1						
	Panel	x: Chip length y: Chip	width z: Chip thickness					
	Chipped	k: Seal width t: Touch	Panel Total thickness a:	LCD side length				
	glass	L: Electrode pad length						
		14.1 General glass chip						
		14.1.1 Chip on panel su	urface and crack betwee	n panels:				
		z: Chip thickness	y: Chip width	x: Chip length				
		Z≦t	$\leq 1/2$ k and not over	$x \le 2MM$				
			viewing area					
		• Unit: mm						
		\odot If there are 2 or more chips, x is the total length of each chip						
		14.1.2 Corner crack:						
		X X X Y						
		z: Chip thickness	y: Chip width	x: Chip length				
		Z≦t	$\leq 1/2$ k and not over	x≦2MM				
			viewing area					
		⊙ Unit: mm						
		\odot If there are 2 or more chips, x is the total length of each chip						

NO.	Item	Item Criterion		
15	Touch Panel(Fish eye, dent and bubble on film)	SIZE(mm)Acceptable Q' ty $\Phi \leq 0.2$ Accept no dense $0.2 < D \leq 0.4$ 5 $0.4 < D \leq 0.5$ 0 $0.5 < D$ 0		
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect for and line distortion ($\leq 2.5\%$), it is acceptable.	ont 1.5	
17	Touch Panel Linearity	Less than 1.5% is acceptable.	1.5	
18	LCD Ripple	Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	1.5	
19	General appearance	 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. 	0.65 0.65 0.65 0.65	

11. Handling Precaution

11.1 Handling of LCM

Avoid external shock.

Don't apply excessive force on the surface.

Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.

Don't operate it above the absolute maximum rating.

Don't disassemble the LCM.

The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.

The modules should be kept in antistatic bags or other containers resistant to static for storage.

The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

11.2 Storage

Store it in an ambient temperature of $25\pm10^{\circ}$ C, and in a relative

humidity of 50±10%RH. Don't expose to sunlight or fluorescent light. Store it in a clean environment, free from dust, active gas, and solvent. Store it in anti-static electricity container.

Store it without any physical load.

11.3 Soldering

Use only soldering irons with proper grounding and no leakage.

Iron: no higher than 280 ± 10 °C and less than 3 sec during hand soldering.

Rewiring: no more than 2 times.

12.PackingMethod

TBD